

Application Note: AN SY8060

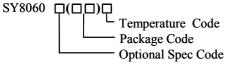
High Efficiency 1.5MHz, Dual 1A **Synchronous Step Down Regulator**

General Description

SY8060 is a dual-output, synchronous step-down DC-DC regulator with high-efficiency 1.5MHz, capable of delivering up to 1A output current per output respectively. SY8060 operates over a wide input voltage range from 2.5V to 5.5V and integrate main switch and synchronous switch with very low RDS(ON) to minimize the conduction loss.

Low output voltage ripple and small external inductor and capacitor sizes are achieved with 1.5MHz switching frequency.

Ordering Information



Ordering Number	Package type	Note
SY8060DCC	DFN3x3-12	1A

Features

- Low R_{DS(ON)} for internal switches (top/bottom): $260 \text{m}\Omega/170 \text{m}\Omega$
- 2.5-5.5V input voltage range
- Typical 40uA quiescent current
- High light load efficiency
- 1.5MHz switching frequency minimizes the external components
- Internal softstart limits the inrush current
- 100% dropout operation RoHS Compliant and Halogen Free
- Compact and thermally enhanced package: DFN3x3-12

Applications

- WiFi Card
- LCD TV
- **GPS**
- Access Point Router
- **Smart Phone**

Typical Applications

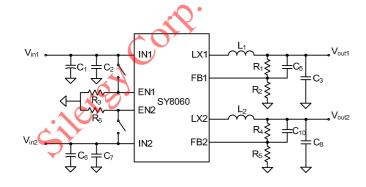


Figure 1.Schematic diagram

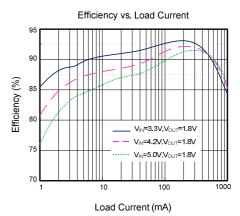
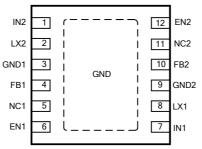


Figure 2. Efficiency vs Load Current



Pinout (Top View)



Top Mark: LXxyz (Device code: LX; x=year code, y=week code, z= lot number code)

Pin Name	DFN3x3-12	Pin Description
EN1	6	Enable controls. Pull high to turn on. Do not float.
EN2	12	$\mathcal{L}^{\mathcal{O}}$
GND1	3	Ground pins.
GND2	9	
LX1	8	Inductor pins. Connect this pin to the switching node of inductor
LX2	2	
IN1	7	Input pins. Decouple IN1 pin to exposed paddle with at least 10uF ceramic
IN2	1	capacitor. Decouple IN2 pin to exposed paddle with at least 10uF ceramic capacitor.
FB1	4	Output Feedback Pins. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage:
FB2	10	Vout1= $0.6*(1+R1/R2)$, Vout2= $0.6*(1+R3/R4)$. Add optional C ₃ (10p-47pF) C ₄ (10p-47pF) to speed up transient response.
NC1	5	No connection (
NC2	11	<i>₹</i> ,
GND	Exposed	Ground pin
	Paddle	

Ab	SO	lu	te	Maxin	num	Ra	tings	(Note 1)

Supply Input Voltage	6V
LX Voltage	0.3V $^{(*1)}$ to V_{IN} $^{(*2)}$
All Other Pins	$V_{IN} + 0.6V$
Power Dissipation, Ph@/TA = 25°C DFN3x3	1.6 W
Package Thermal Resistance (Note 2)	
DFN3x3, θ JA	
DFN3x3, θ JC	
Junction Temperature Range	150°C
Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	
(*1) LX Voltage tested down to -3V<20ns under 1GHz bandwidth	
(*2) LX Voltage tested up to +7V<20ns under 1GHz bandwidth	

Recommended Operating Conditions (Note 3)

EN, IN, FB pins	2.5V to 5.5V
LX nin	2 5V to 6V





Junction Temperature Range	40°C to 125°C
Ambient Temperature Range	40°C to 85°C

Electrical Characteristics

 $(V_{IN} = 5V, V_{OUT} = 2.5V, L = 2.2uH, C_{OUT} = 10uF, T_A = 25^{\circ}C, unless otherwise specified)$

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Input Voltage Range	V_{IN}		2.5		5.5	V
Quiescent Current	I_Q	IOUT=0, $V_{FB}=V_{REF} \cdot 105\%$		40		μΑ
Shutdown Current	I_{SHDN}	EN=0		0.1	1	μΑ
Feedback Reference Voltage	$V_{ m REF}$		0.588	0.6	0.612	V
Adjustable Output Voltage Range	V_{OUT}	(Note4)	V_{REF}	Ì	V_{IN} - ΔV	V
FB Input Current	I_{FB}	$V_{FB}=V_{IN}$	-50		50	nA
PFET RON	$R_{DS(ON),P}$		KC	260		mΩ
NFET RON	R _{DS(ON)} ,N		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	170		mΩ
PFET Current Limit	I_{LIM}	J-2	1.3		1.9	A
EN rising threshold	V_{ENH}		1.5			V
EN falling threshold	V_{ENL}				0.4	V
Input UVLO threshold	$V_{\rm UVLO}$				2.5	V
UVLO hysteresis	V_{HYS}			0.1		V
Oscillator Frequency	Fosc		1.2	1.5	1.8	MHz
Min ON Time				80		ns
Max Duty Cycle			100	·		%
Soft Start Time	T_{SS}			1		ms
Thermal Shutdown Temperature	T_{SD}			160		°C
Thermal Shutdown Hysteresis	T_{HYS}			15	_	°C

Note 1: **Note 1**: Stresses beyond "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

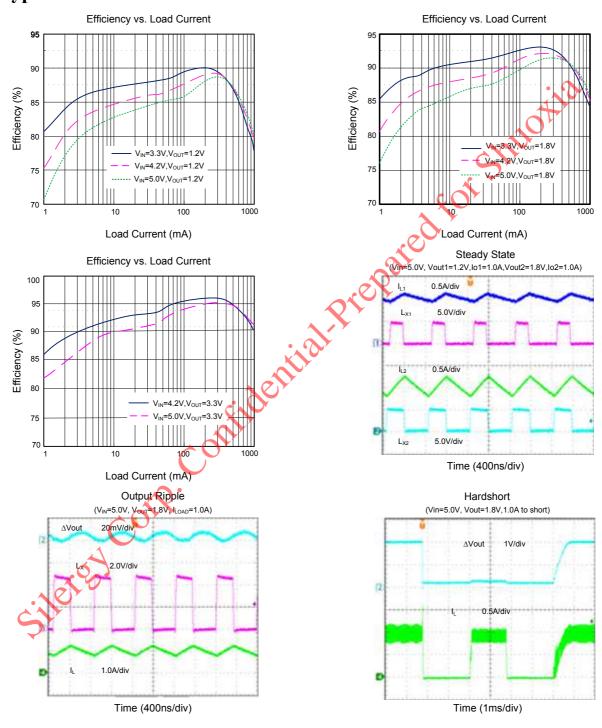
Note 2: θ JA is measured in the natural convection at $T_A = 25^{\circ}$ C on a low effective single layer thermal conductivity test board of JEDEC 51-3/thermal measurement standard. Exposed Paddle of DFN package is the case position for θ JC measurement.

Note 3: The device is not guaranteed to function outside its operating conditions.

Note4: Output voltage is limited by Min On Time. It is guaranteed by design. $\triangle V = I_{OUT} \times P_{RDS(ON)}$.

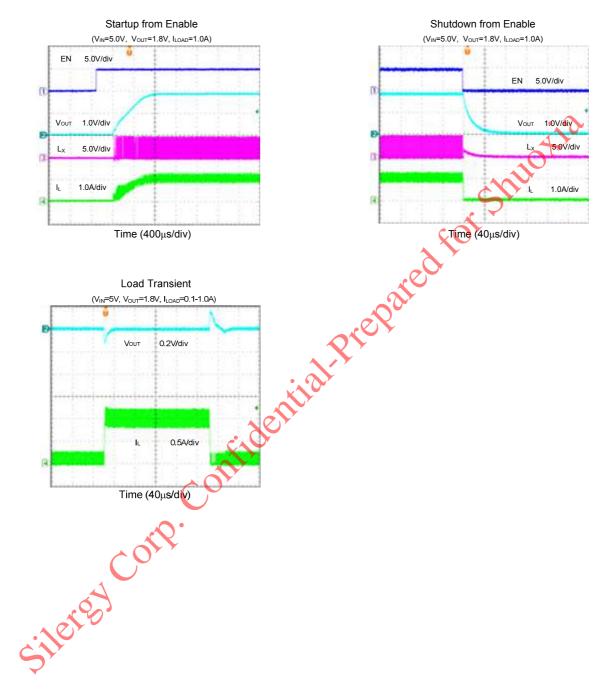


Typical Performance Characteristics











Operation

SY8060 is a high-efficiency 1.5MHz synchronous stepdown DC-DC converters capable of delivering up to 1A output current. It operates over a wide input voltage range from 2.5V to 5.5V and integrates main switch and synchronous switch with very low R_{DS(ON)} to minimize the conduction loss.

Applications Information

Because of the high integration in the SY8060 IC, the application circuit based on this regulator IC is rather simple. Only input capacitor C_{IN}, output capacitor C_{OUT}, output inductor L and feedback resistors (R1 and R2) need to be selected for the targeted applications specifications.

Feedback resistor dividers R1 and R2:

Choose R1 and R2 to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both R1 and R2. A value of between $100k\Omega$ and $1M\Omega$ is highly recommended for both resistors. If $R2=120k\Omega$ is chosen, then R1 can be calculated to be:

$$R_1 = \frac{(V_{OUT} - 0.6 \, V) \cdot R_2}{0.6 V}$$

Input capacitor C_{IN}:

SY8060 is a co-package IC integrated with two dies. It is strongly recommended to decouple IN1 to GND paddle with at least 10uF ceramic cap and decouple IN2 to GND paddle with at least 10uF ceramic cap. Place these ceramic capacitors really close to IN1 and GND pins, IN2 to GND pins to minimize the potential noise problem. Care should be taken to minimize the loop area formed by CIN, and IN/GND pins.

Output capacitor C_{OUT}:

The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X7R or better grade ceramic capacitor with 6V rating and greater than 4.7uF capacitance.

Output inductor L:

There are several considerations in choosing this

1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{\text{OUT}}(1 - V_{\text{OUT}}/V_{\text{IN,MAX}})}{F_{\text{SW}} \times I_{\text{OUT,MAX}} \times 40\%}$$

where Fsw is the switching frequency and Iout,max is the maximum load current.

The SY8060 regulator IC is quite tolerant of different ripple current amplitude. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

2) The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT, MIN} > I_{OUT, MAX} + \underbrace{V_{OUT}(1-V_{OUT}/V_{IN, MAX})}_{2 \cdot F_{SW} \cdot L}$$
 3) The DCR of the inductor and the core loss at the

switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with DCR<50mohm to achieve a good overall efficiency.

Load Transient Considerations:

SY8060 regulator IC integrates the compensation components to achieve good stability and fast transient responses. In some applications, adding a 22pF ceramic cap in parallel with R1 may further speed up the load transient responses and is thus recommended for applications with large load transient step requirements.

Layout Design:

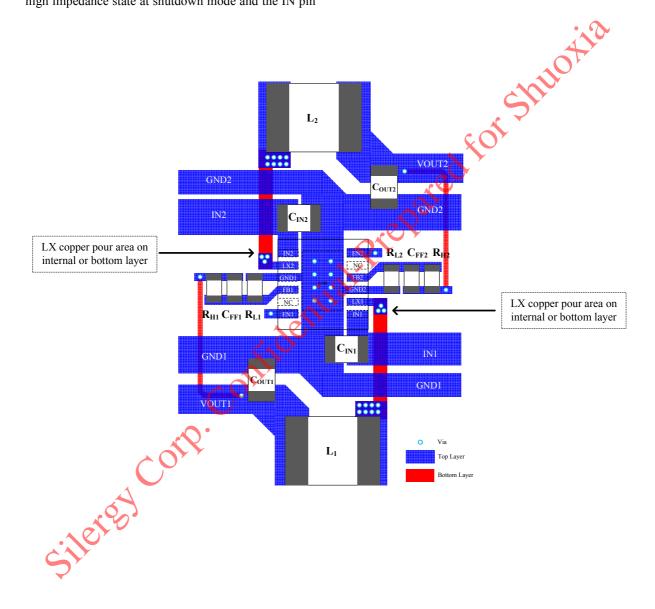
The layout design of SY8060 regulator is relatively simple. For the best efficiency and minimum noise problems, we should place the following components close to the IC: C_{IN}, L, R1 and R2.

- 1) It is desirable to maximize the PCB copper area connecting to GND pin to achieve the best thermal and noise performance. If the board space allowed, a ground plane is highly desirable.
- 2) It is strongly recommended to decouple IN1 to GND paddle with at least 10uF ceramic cap and decouple IN2 to GND paddle with at least 10uF ceramic cap. Place these ceramic capacitors really close to IN1 and GND pins, IN2 to GND pins to minimize the potential noise problem. The loop area formed by CIN and GND must be minimized.
- 3) The PCB copper area associated with LX pin must be minimized to avoid the potential noise problem.



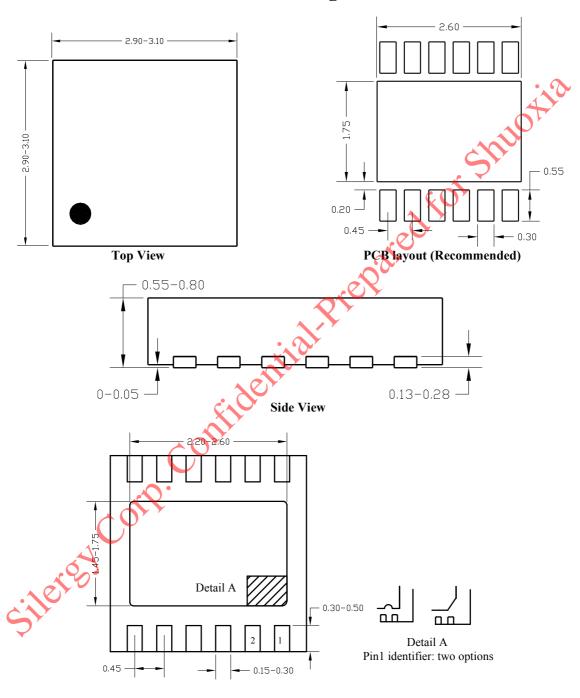
- 4) The components R1 and R2, and the trace connecting to the FB pin must NOT be adjacent to the LX net on the PCB layout to avoid the noise problem.
- 5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the IN pin

is connected directly to a power source such as a LiIon battery, it is desirable to add a pull down 1Mohm resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator at shutdown mode





DFN3x3-12 Package outline



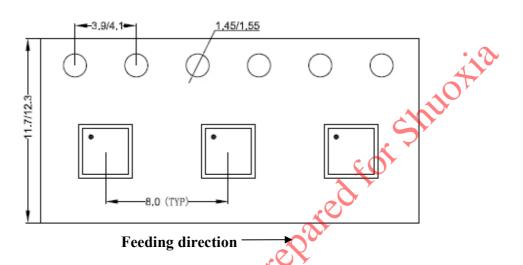
Bottom View

Notes: All dimensions are in millimeters and exclude mold flash & metal burr.

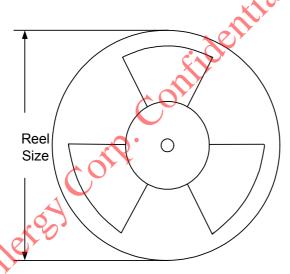


Taping & Reel Specification

1. DFN3x3-12 taping orientation



2. Carrier Tape & Reel specification for packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
DFN3x3	12	8	13"	400	400	5000

3. Others: NA